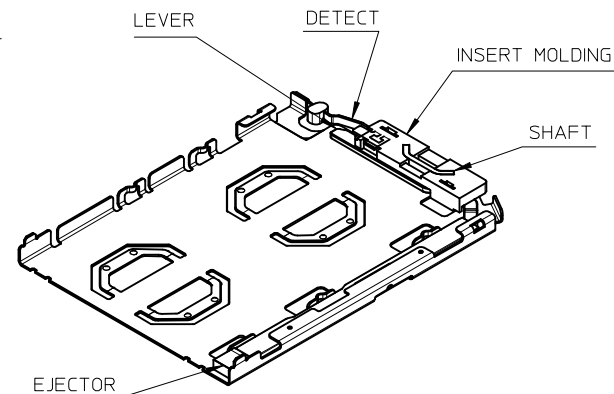
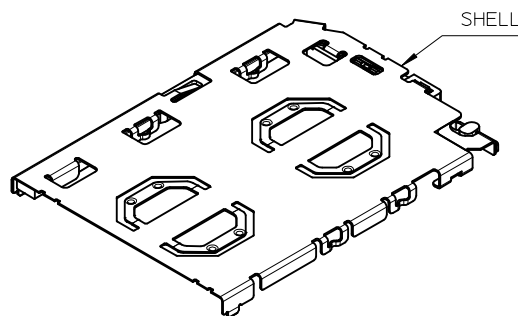


10 9 8 7 6 5 4 3 2 1

THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.



NOTES:

1. MATERIALS:

INSERT MOLD HOUSING: LCP, UL94V-0;
LEVER, SHAFT, EJECTOR, SHELL: STAINLESS STEEL;
DETECT SPRING: COPPER ALLOY;

2. FINISHES:

DETECT SPRING:

1.27um MIN. NICKEL UNDERPLATING OVERALL;
0.127um MIN. GOLD PLATING ON CONTACT AREA;
1.27 um MIN. TIN PLATING ON SOLDERING TAIL;

SHELL:

1.27um MIN NICKEL UNDERPLATING OVERALL;
0.025um MIN GOLD PLATING ON CONTACT AREA AND SOLDERING AREA;
SHAFT: 1.27um MIN TIN ON SOLDERING TAIL;

3. PRODUCT SPECIFICATION: PS-151031-001;

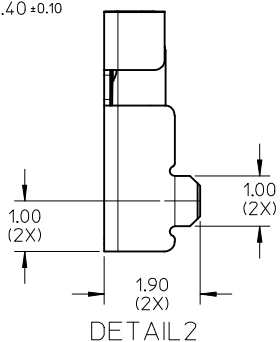
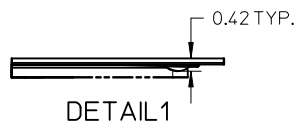
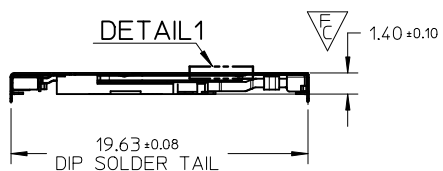
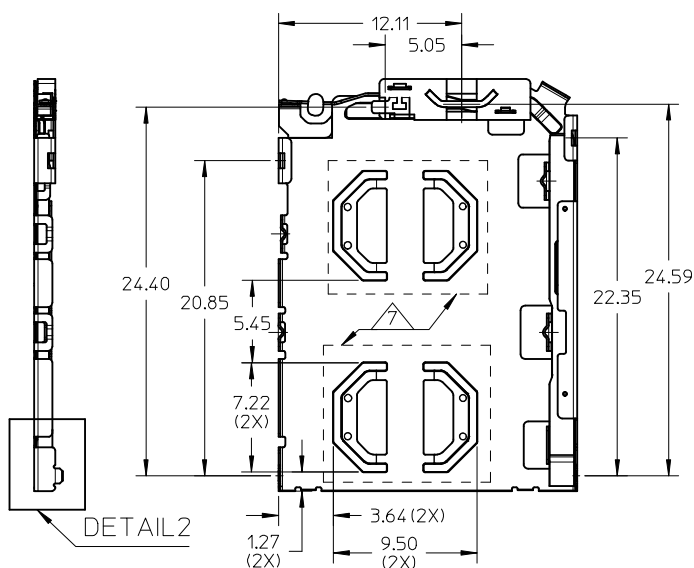
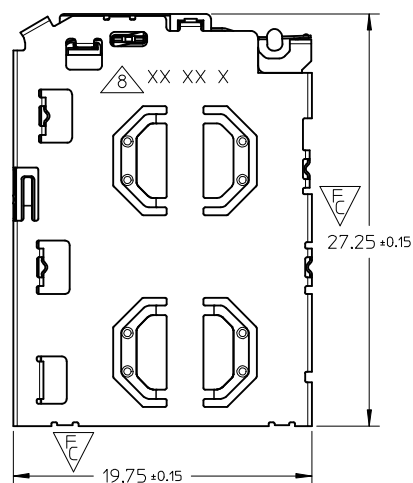
4. PACKAGING SPECIFICATION: PK-151031-001;PK-151032-001

5. SOLDER TAIL COPLANARITY: 0.10 MM MAX BEFORE REFLOW

6. THIS PART IS A FRAME ONLY, IT SHOULD BE USED TOGETHER WITH 0.35MM BLOCK SIM 151032 FOR AN ENTIRE SIM POP OUT SYSTEM;
7. 0.10 MINIMUM KEEP OUT ZONE FROM TOP SURFACE OF SHELL DURING INSERTION AND WITHDRAWAL OF TRAY (WITH SIM CARD)

8. DATE CODE PRINTED: XX XX X

DAY
WEEK
YEAR



CHANGE BLOCK SIM AND TRAY
EC NO: S2014-0434
DRWN: JZENG 2013/11/04
CHKD: JTAN02 2014/01/02
APPR: KHLIM 2014/01/27

QUALITY SYMBOLS
F_A=0
F_G=4
F_P=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± 0.20	± ---
0 PLACE	± ---	± ---

ANGULAR ± 3 °
DRAFT WHERE APPLICABLE
MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY

DRAWN BY	DATE
JZENG	2013/11/04
CHECKED BY	DATE
JTAN02	2013/12/05
APPROVED BY	DATE
KHLIM	2014/01/27

MATERIAL NO.
1510310001

SCALE
NTS

DESIGN UNITS
METRIC

THIRD ANGLE PROJECTION

TITLE
DUAL MICRO SIM FRAME
1.40 H

molex

DOCUMENT NO.
SD-151031-0001

SHEET NO.
1 OF 5

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

E

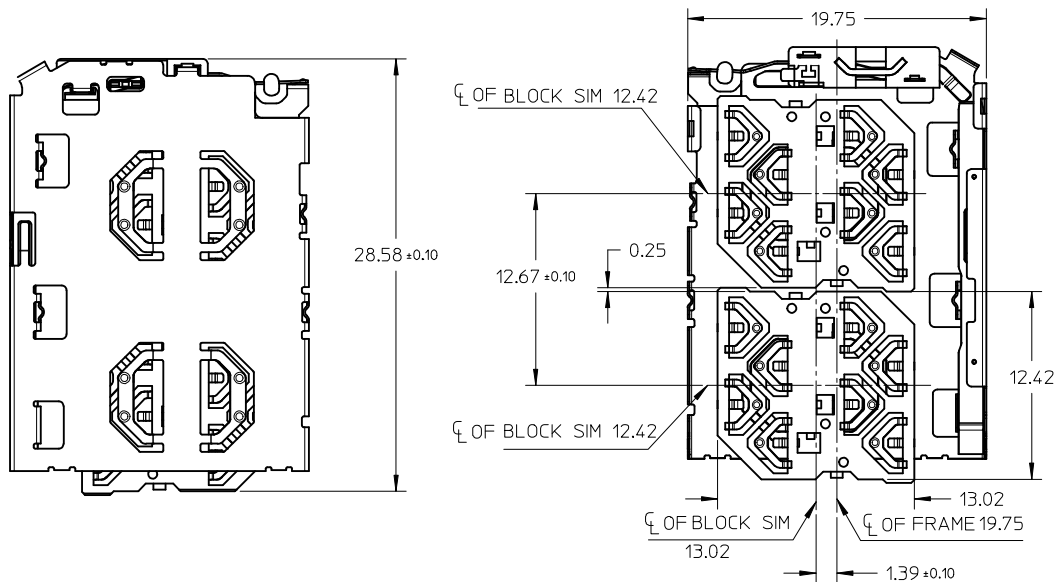
D

C

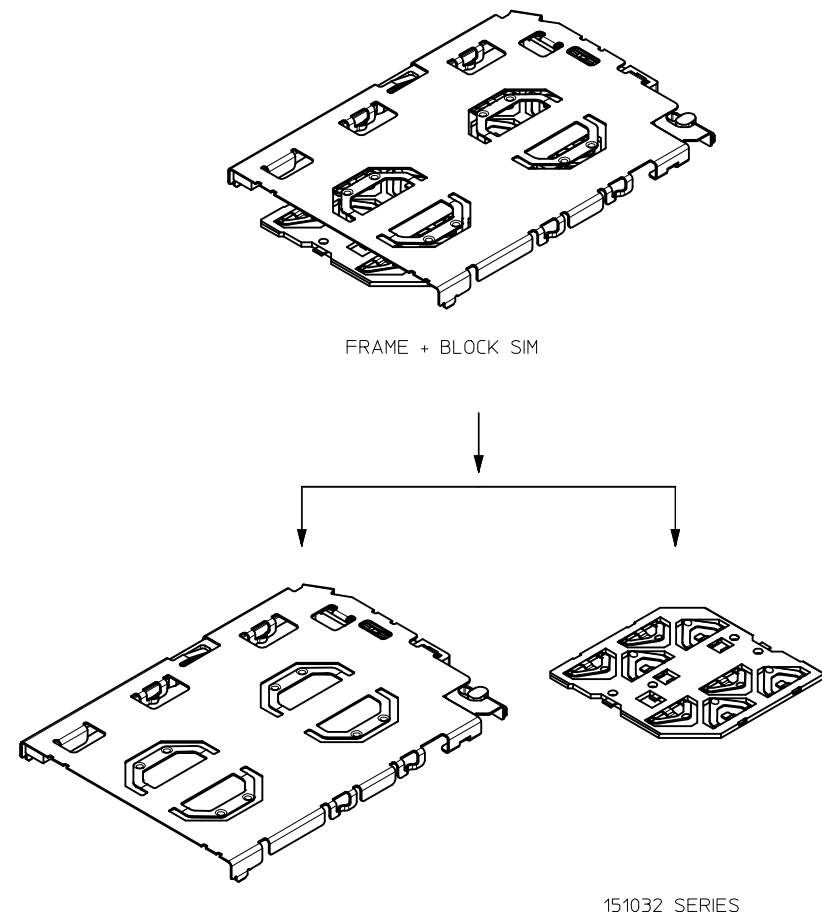
B

A

SIM CONNECTOR
(WITH 151032 BLOCK SIM CONNECTOR)



SIM CONNECTOR BOM



THIS DESIGN IS BASED ON DESIGN OBJECTIVES
AND IS STRICTLY TENTATIVE. IT MAY CHANGE
BASED ON RESULTS OF ADDITIONAL DESIGN
REVIEWS & VERIFICATIONS.

SEE SHEET1 EC NO: S2014-0434 DRWN: ZENG CHKD: TAN02 APPR: KHLIM	DESCRIPTION REV	QUALITY SYMBOLS FA=0 FG=0 FP=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
				mm	INCH	DRAWN BY JZENG	DATE 2013/11/04	TITLE DUAL MICRO SIM FRAME 1.40 H				
			4 PLACES	± ---	± ---	CHECKED BY JTAN02	DATE 2013/12/05					
			3 PLACES	± ---	± ---	APPROVED BY KHLIM	DATE 2014/01/27					
			2 PLACES	± 0.20	± ---	MATERIAL NO. 1510310001		DOCUMENT NO. SD-151031-0001		SHEET NO. 2 OF 5		
			1 PLACE	± 0.20	± ---							
0 PLACE	± ---	± ---										
			ANGULAR ± 3 °									
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

10

9

8

7

6

5

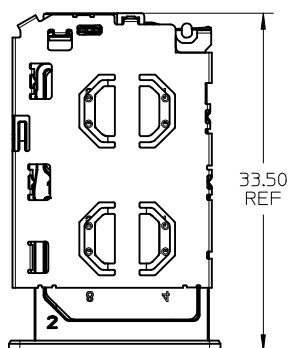
4

3

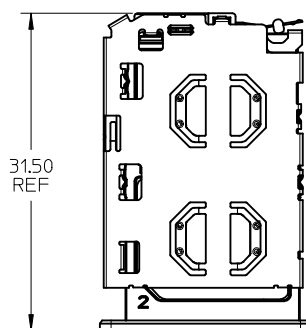
2

1

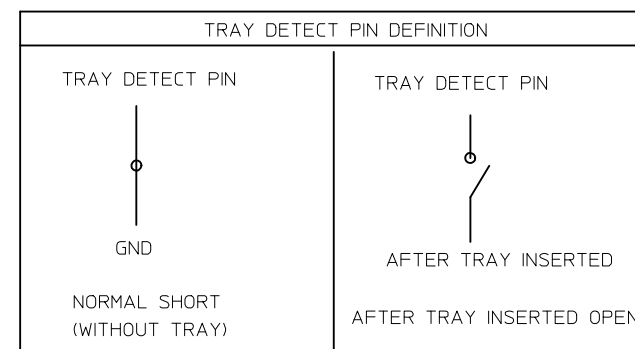
SIM CONNECTOR FRAME AND TRAY



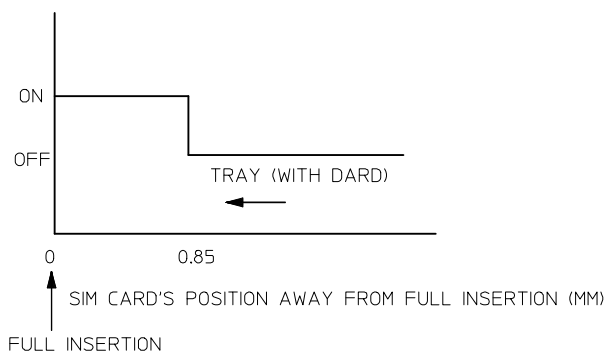
TRAY EJECTED POSITION



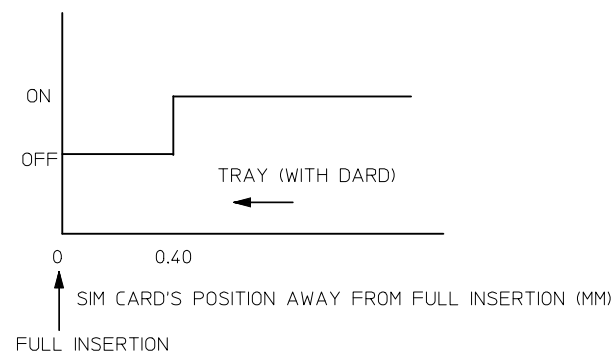
TRAY INSERTION POSITION



SIGNAL PIN



DETECT SWITCH PIN



ENTER DESCRIPTION EC NO: S2014-0434 DRWN: JZENG CHKD: JTAN02 APPR: KHLIM	DESCRIPTION REV 7	QUALITY SYMBOLS ▽_A=0 ▽_G=0 ▽_P=0	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION						
				mm	INCH	DRAWN BY JZENG	DATE 2013/11/04	TITLE DUAL MICRO SIM FRAME 1.40 H								
			4 PLACES ± ---	± ---	CHECKED BY JTAN02	DATE 2013/12/05										
			3 PLACES ± ---	± ---	APPROVED BY KHLIM	DATE 2014/01/27	molex									
			2 PLACES ± 0.20	± ---	MATERIAL NO. 1510310001									DOCUMENT NO. SD-151031-0001		SHEET NO. 3 OF 5
			1 PLACE ± 0.20	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS											
0 PLACE ± ---	± ---	SIZE A3					THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

9

8

7

6

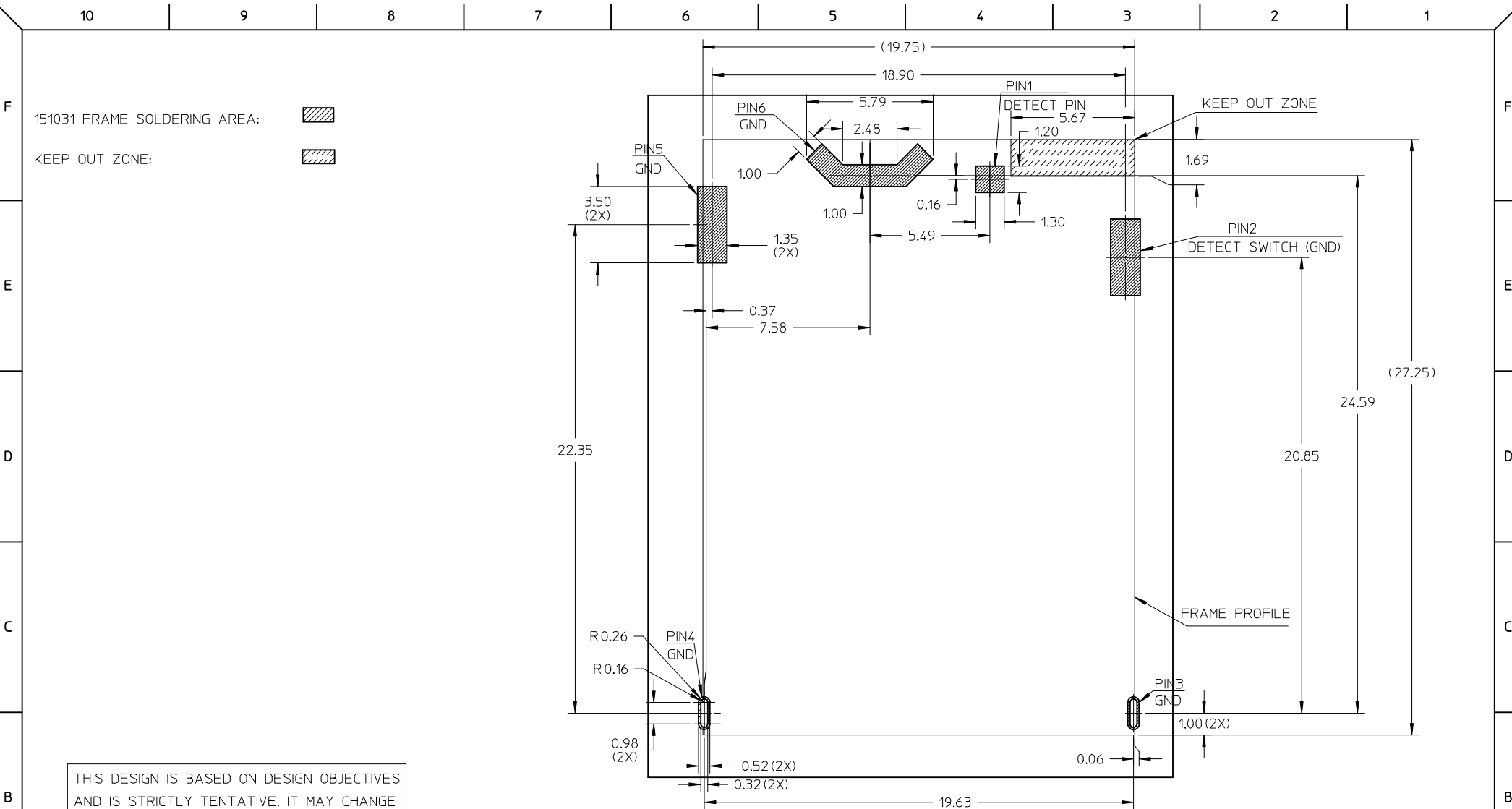
5

4

3

2

1

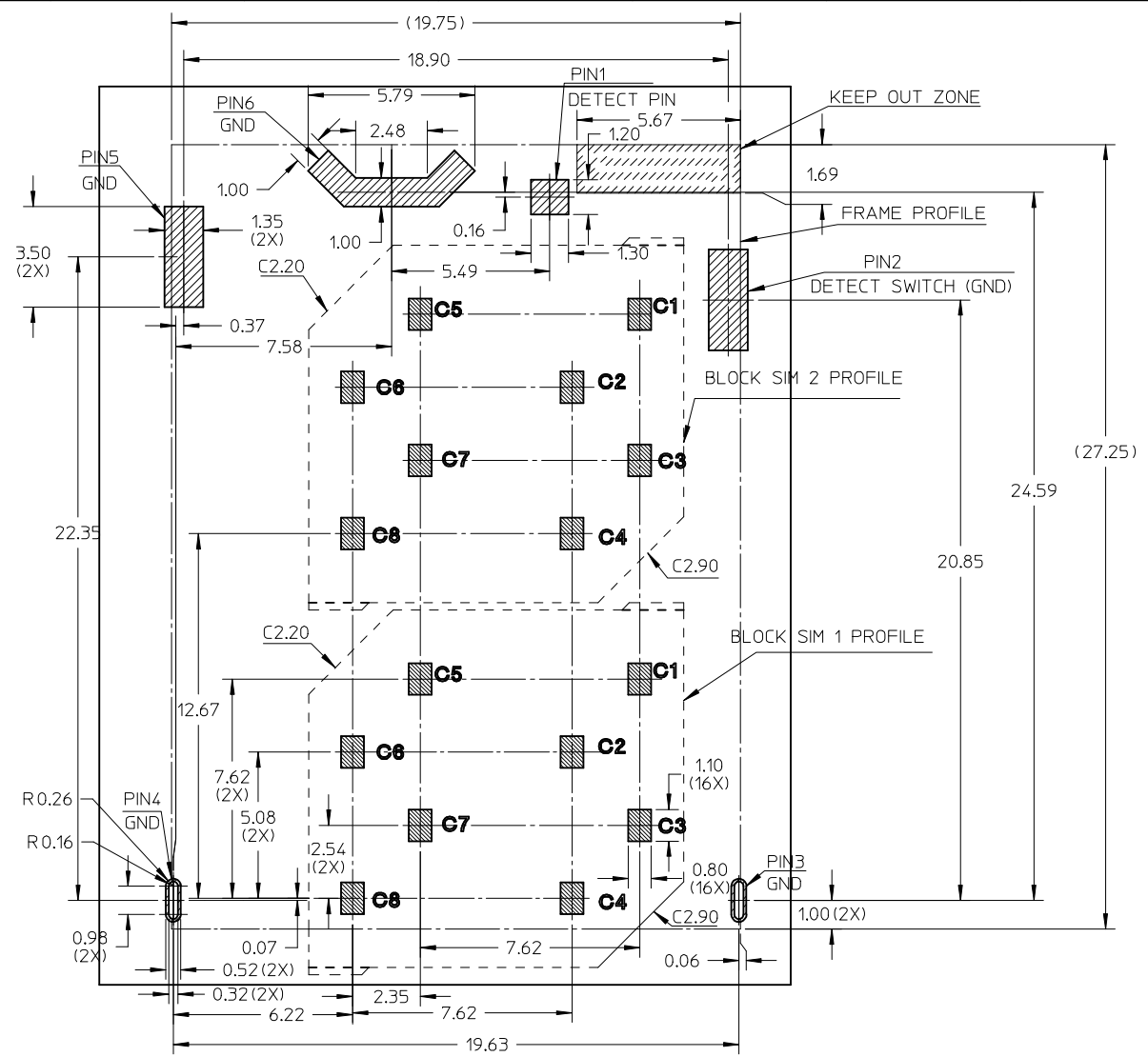


THIS DESIGN IS BASED ON DESIGN OBJECTIVES
AND IS STRICTLY TENTATIVE. IT MAY CHANGE
BASED ON RESULTS OF ADDITIONAL DESIGN
REVIEWS & VERIFICATIONS.

RECOMMENDED PCB LAYOUT: TOLERANCE ± 0.05
RECOMMENDED PCB THICKNESS: 0.80MM
RECOMMENDED STENCIL THICKNESS: 0.10MM

SEE SHEET 1 EC NO: S2014-0434 DRWN: JZENG CHKD: JTAN02 APPR: KHLIM	DESCRIPTION REV	QUALITY SYMBOLS 	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
				mm	INCH	DRAWN BY JZENG	DATE 2013/11/04	TITLE DUAL MICRO SIM FRAME 1.40 H				
			4 PLACES	± ---	± ---	CHECKED BY JTAN02	DATE 2013/12/05					
			3 PLACES	± ---	± ---	APPROVED BY KHLIM		DATE 2014/01/27	molex			
			2 PLACES	± 0.20	± ---	MATERIAL NO. 1510310001		DOCUMENT NO. SD-151031-0001				
			1 PLACE	± 0.20	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
0 PLACE	± ---	± ---	SIZE A3									

151031 FRAME SOLDERING AREA: 
151032 BLOCK SIM SOLDERING AREA: 
KEEP OUT ZONE: 



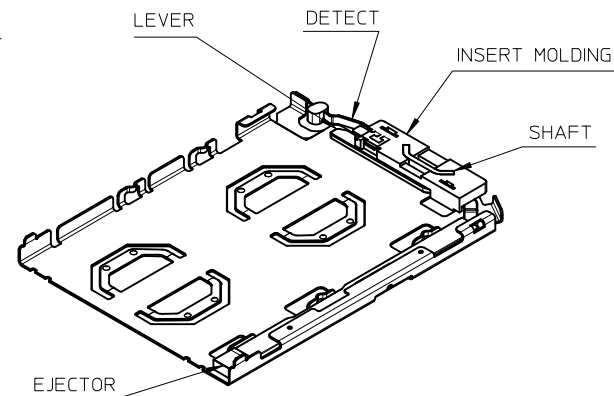
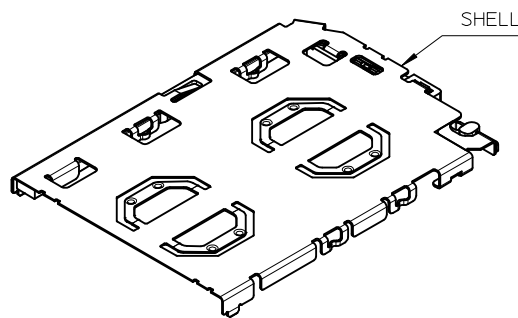
THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.

RECOMMENDED PCB LAYOUT: TOLERANCE ±0.05
RECOMMENDED PCB THICKNESS: 0.80MM
RECOMMENDED STENCIL THICKNESS: 0.10MM

SEE SHEET 1 EC NO: S2014-0434 DRWN: JZENG CHKD: JTAN02 APPR: KHL IM 7	DESCRIPTION	QUALITY SYMBOLS F=0 F=0 F=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	DUAL MICRO SIM FRAME 1.40 H molex	
				mm	INCH	DRAWN BY JZENG	DATE 2013/11/04	TITLE			
			4 PLACES	± ---	± ---	CHECKED BY JTAN02	DATE 2013/12/05				
			3 PLACES	± ---	± ---	APPROVED BY KHL IM	DATE 2014/01/27				
			2 PLACES	± 0.20	± ---						
			1 PLACE	± 0.20	± ---						
	0 PLACE	± ---	± ---								
			ANGULAR ± 3 °		MATERIAL NO. 1510310001	DOCUMENT NO. SD-151031-0001		SHEET NO. 5 OF 5			
REV			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1

THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.



NOTES:

1. MATERIALS:

INSERT MOLD HOUSING: LCP, UL94V-0;

LEVER, SHAFT, EJECTOR, SHELL: STAINLESS STEEL;

DETECT SPRING: COPPER ALLOY;

2. FINISHES:

DETECT SPRING:

1.27um MIN. NICKEL UNDERPLATING OVERALL;

0.127um MIN. GOLD PLATING ON CONTACT AREA;

1.27 um MIN. TIN PLATING ON SOLDERING TAIL;

SHELL:

1.27um MIN NICKEL UNDERPLATING OVERALL;

0.025um MIN GOLD PLATING ON CONTACT AREA AND SOLDERING AREA;

SHAFT: 1.27um MIN TIN ON SOLDERING TAIL;

3. PRODUCT SPECIFICATION: PS-151031-001;

4. PACKAGING SPECIFICATION: PK-151031-001;PK-151032-001

5. SOLDER TAIL COPLANARITY: 0.10 MM MAX BEFORE REFLOW

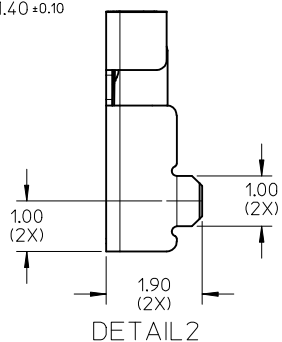
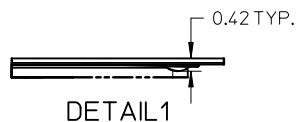
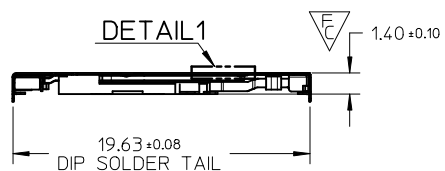
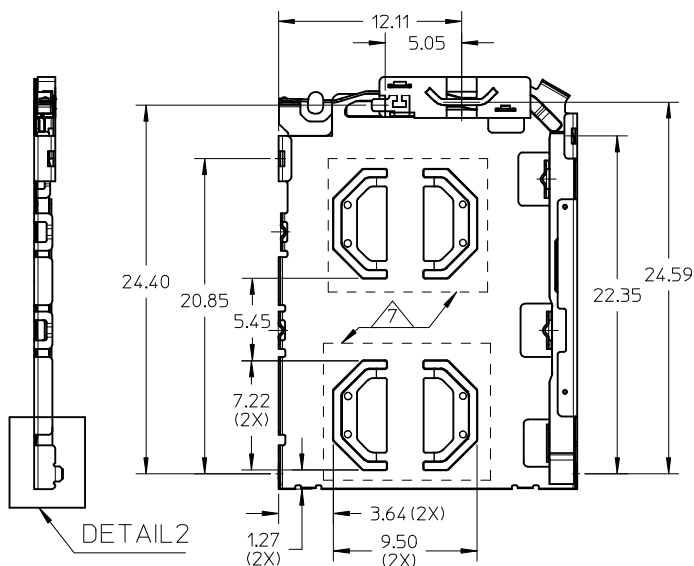
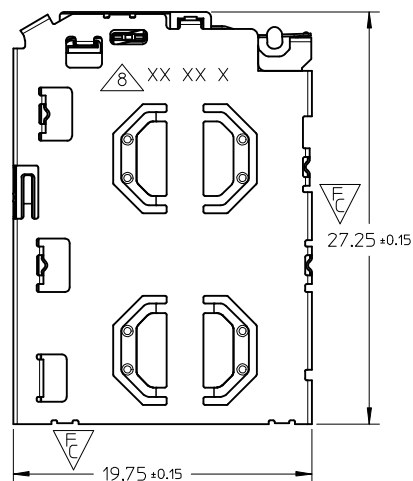
6. THIS PART IS A FRAME ONLY, IT SHOULD BE USED TOGETHER WITH

0.35MM BLOCK SIM 151032 FOR AN ENTIRE SIM POP OUT SYSTEM;

7. 0.10 MINIMUM KEEP OUT ZONE FROM TOP SURFACE OF SHELL DURING INSERTION AND WITHDRAWAL OF TRAY (WITH SIM CARD)

8. DATE CODE PRINTED: XX XX X

DAY
WEEK
YEAR



UPDATED DRAWING
EC NO: S2014-0434
2013/12/13
DRWN: JZENG
CHKD: JIAN02
2014/01/02
APPR: KHLIM
2014/01/27

QUALITY SYMBOLS
F_A=0
F_G=4
F_P=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± 0.20	± ---
0 PLACE	± ---	± ---

ANGULAR ± 3 °
DRAFT WHERE APPLICABLE
MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY

DRAWN BY	DATE
JZENG	2013/12/13

CHECKED BY	DATE
KHLIM	2014/01/27

APPROVED BY	DATE
KHLIM	2014/01/27

MATERIAL NO.
1510310001

SCALE
NTS

DESIGN UNITS
METRIC

THIRD ANGLE PROJECTION

TITLE
DUAL MICRO SIM FRAME
1.40H

molex

DOCUMENT NO.
SD-151031-0002

SHEET NO.
1 OF 4

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

F

E

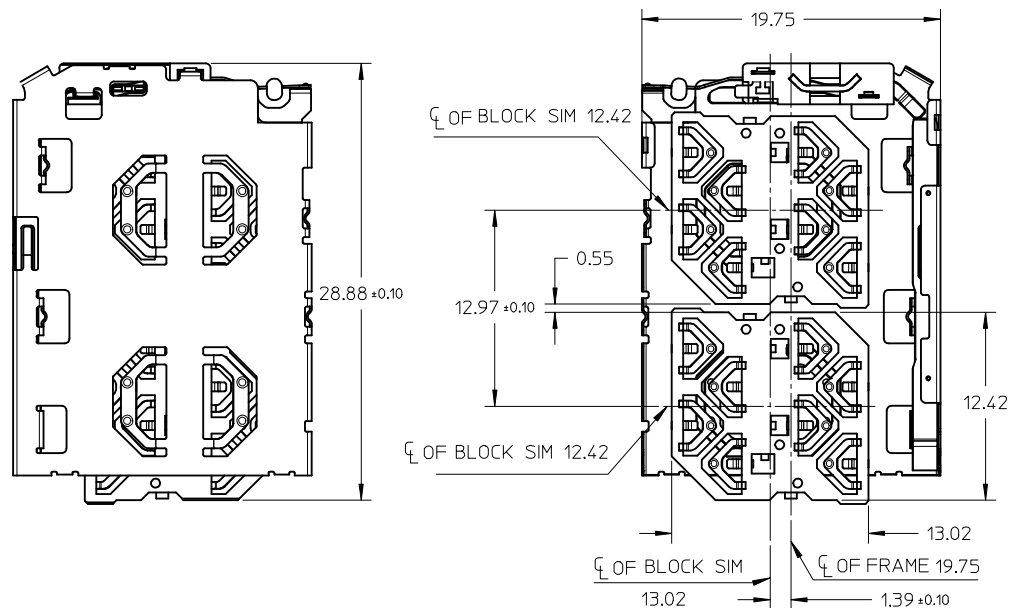
D

C

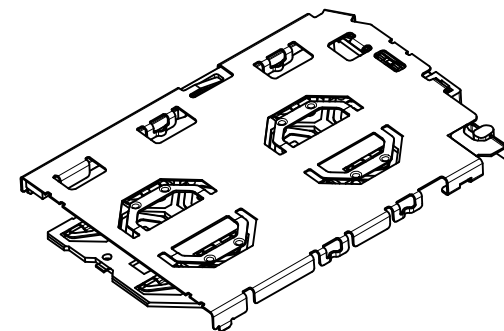
B

A

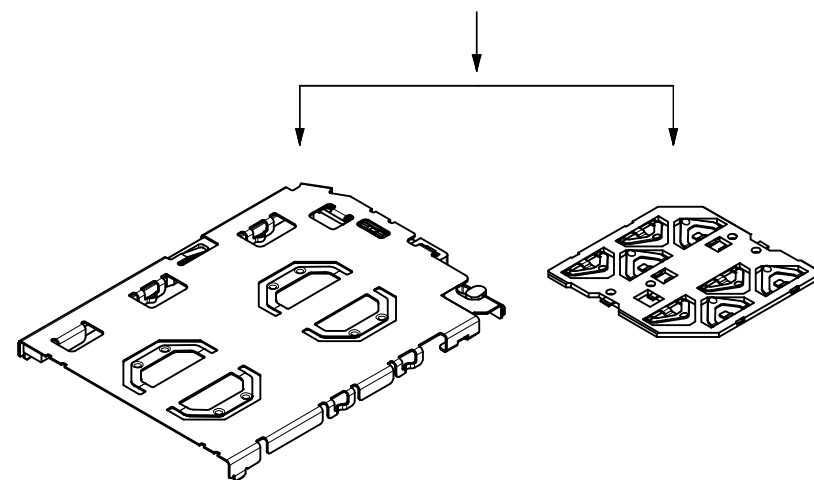
SIM CONNECTOR
(WITH 151032 BLOCK SIM CONNECTOR)



SIM CONNECTOR BOM



FRAME + BLOCK SIM



151032 SERIES

151031 SERIES

THIS DESIGN IS BASED ON DESIGN OBJECTIVES
AND IS STRICTLY TENTATIVE. IT MAY CHANGE
BASED ON RESULTS OF ADDITIONAL DESIGN
REVIEWS & VERIFICATIONS.

SEE SHEET1
EC NO: S2014-0434
2013/12/13
DRWN: JZENG
2014/01/02
CHKD: JIAN02
APPR: KHL IM
2014/01/27

QUALITY
SYMBOLS
F_A=0
F_G=0
F_P=0

GENERAL TOLERANCES
(UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± 0.20	± ---
0 PLACE	± ---	± ---

ANGULAR ± 3 °
DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY

DRAWN BY	DATE
JZENG	2013/12/13

CHECKED BY	DATE

APPROVED BY	DATE
KHL IM	2014/01/27

MATERIAL NO.
1510310001

SIZE
A3

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
NTS	METRIC	

TITLE
DUAL MICRO SIM FRAME
1.40H

molex

DOCUMENT NO.
SD-151031-0002

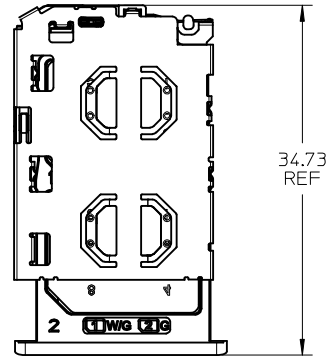
SHEET NO.
2 OF 4

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX
INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

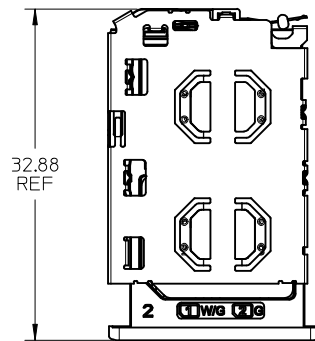
9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

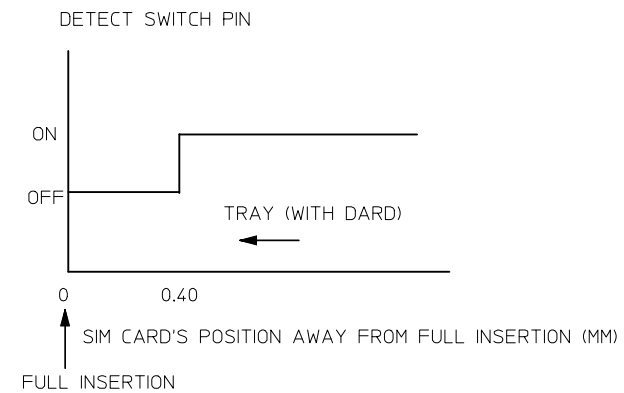
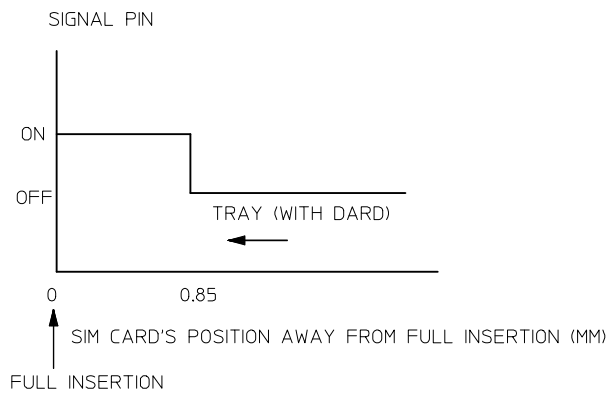
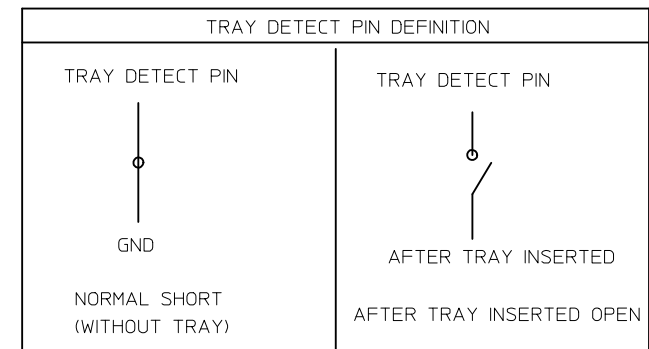
SIM CONNECTOR FRAME AND TRAY



TRAY EJECTED POSITION

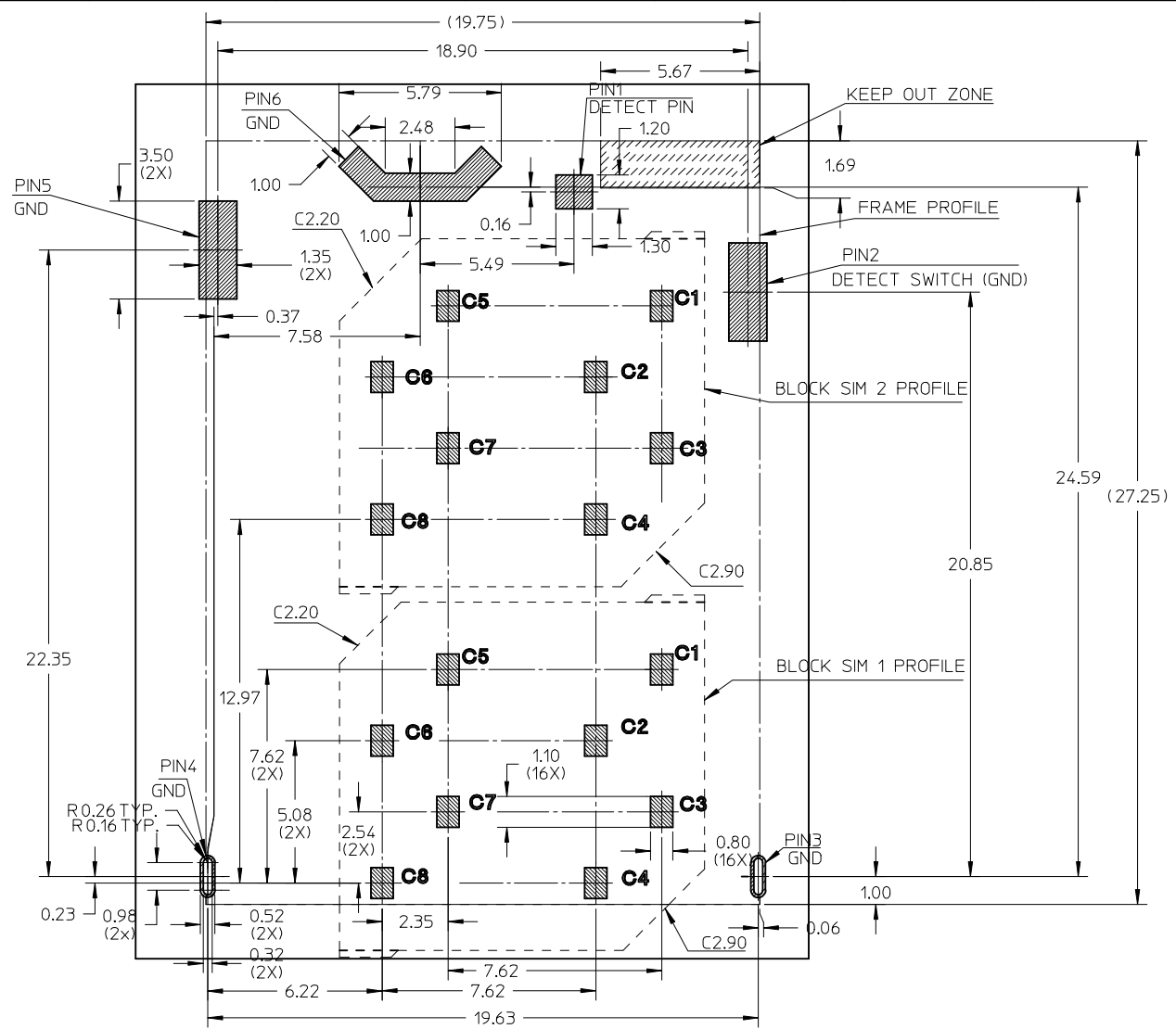


TRAY INSERTION POSITION



SEE SHEET 1 EC NO: S2014-0434 DRWN: JZENG 2013/12/13 CHKD: JIAN02 2014/01/02 APPR: KHLIM 2014/01/27	DESCRIPTION	QUALITY SYMBOLS FA=0 FG=0 FP=0	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION						
				mm	INCH	DRAWN BY JZENG	DATE 2013/12/13	TITLE DUAL MICRO SIM FRAME 1.40H								
			4 PLACES	± ---	± ---	CHECKED BY	DATE									
			3 PLACES	± ---	± ---	APPROVED BY KHLIM		DATE 2014/01/27	molex							
			2 PLACES	± 0.20	± ---											
			1 PLACE	± 0.20	± ---											
			0 PLACE	± ---	± ---											
			ANGULAR ± 3 °			MATERIAL NO.		DOCUMENT NO.					SHEET NO.			
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			1510310001		SD-151031-0002					3 OF 4			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																

151031 FRAME SOLDERING AREA:
151032 BLOCK SIM SOLDERING AREA:
KEEP OUT ZONE:



THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.

RECOMMENDED PCB LAYOUT: TOLERANCE ±0.05
RECOMMENDED PCB THICKNESS: 0.80MM
RECOMMENDED STENCIL THICKNESS: 0.10MM

SEE SHEET 1 EC NO: S2014-0434 DRWN: JZENG CHKD: JIAN02 APPR: KHL IM	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
				mm	INCH	DRAWN BY JZENG	DATE 2013/12/13	TITLE DUAL MICRO SIM FRAME 1.40H				
						CHECKED BY	DATE					
						APPROVED BY KHL IM	DATE 2014/01/27	molex				
						MATERIAL NO. 1510310001	DOCUMENT NO. SD-151031-0002					
			ANGULAR ± 3 °									
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS									
			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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